L Number	Hits	Search Text	DB .	Time stamp
Number	541619	nickel ni	USPAT;	2004/01/18
, <del>-</del>			US-PGPUB;	17:36
	Ì		EPO; JPO;	
			DERWENT;	!
•			IBM_TDB	
2	993	buffer with (nickel ni)	USPAT;	2004/01/18
			US-PGPUB; EPO; JPO;	17:36
İ			DERWENT;	·
	•		IBM TDB	
. 3	13274809	"5" "6" "7" "8" "9" "10" with (buffer	USPAT;	2004/01/18
:		with (nickel ni))	US-PGPUB;	17:37
	Ì		EPO; JPO;	!
1			DERWENT;	.
1	2512	   ("5" "6" "7" "8" "9" "10")	IBM_TDB	. 2204/01/19
4	. 2518	("5" "6" "/" "8" "9" "10") With (buffer ) with (nickel ni))	USPAT; US-PGPUB;	2004/01/18 18:29
:		with (nicker hi);	EPO; JPO;	1 10.23
	1		DERWENT;	j
:	1	:	IBM_TDB	
; 5	2026	(micro micrometer mm nm) with (("5" "6"	USPĀT;	2004/01/18
	ļ	"7" "8" "9" "10") with (buffer with	US-PGPUB;	17:44
İ		(nickel ni)))	EPO; JPO;	•
;			DERWENT;	
6	. 3	(chip semiconductor die ic (integrated	IBM_TDB   USPAT;	1 2004/01/18
C		adj circuit) dice) same ((micro	US-PGPUB;	i 17:45
		micrometer mm nm) with (("5" "6" "7" "8"	EPO; JPO;	
i		"9" "10") with (buffer with (nickel	DERWENT;	
<u> </u>	!	[ni))))	IBM_TDB	İ
7	2086	(thickness measurement thick micro   micrometer mm nm) with (("5" "6" "7" "8"	USPAT;	2004/01/18
I		"9" "10") with (buffer with (nickel ni)))	US-PGPUB; EPO; JPO;	18:30
		J 10 ) With (baller with (hicker hi)))	DERWENT;	
		•	IBM TDB	1
8	13	(chip semiconductor die ic (integrated	USPAT;	2004/01/18
İ		adj circuit) dice) same ((thickness	US-PGPUB;	18:31
į	:	measurement thick micro micrometer mm nm)	EPO; JPO;	!
ļ	1	with (("5" "6" "7" "8" "9" "10") with   (buffer with (nickel ni))))	DERWENT;	
9	. 1	(purier wron (urcker UT))))	IBM_TDB USPAT	2004/01/18
		i	. 552111	18:14
10	141350	("5" "6" "7" "8" "9" "10") with (nickel	USPAT;	2004/01/18
i	:	ni)	US-PGPUB;	18:29
1,	i		EPO; JPO;	}
	!		DERWENT;	
11	53830	(thickness measurement thick micro	<pre>IBM_TDB 'USPAT;</pre>	: 2004/01/18
i	33030	micrometer mm. nm) with (nickel ni)	US-PGPUB;	18:30
}	1		EPO; JPO;	10.50
			DERWENT;	
,	•		IBM_TDB	
12	3954	(chip semiconductor die ic (integrated	'USPAT;	2004/01/18
i		<pre>adj circuit) dice) same ((thickness measurement thick micro micrometer mm nm)</pre>	US-PGPUB;	18:31
1		with (nickel ni))	EPO; JPO; DERWENT;	
İ	!	,	IBM TDB	[
13	74	((chip semiconductor die ic (integrated	USPAT;	2004/01/18
		adj circuit) dice) same ((thickness	US-PGPUB;	18:31
	!	measurement thick micro micrometer mm nm)	EPO; JPO;	
1	ļ	with (nickel ni))) same buffer	DERWENT;	1
l	<del>-</del>	·	LIBM_TDB	.!